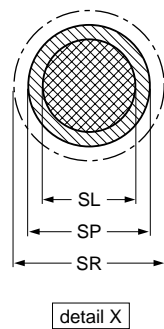**Footprint information for reflow soldering of LFBGA296 package**   **SOT1107-1**
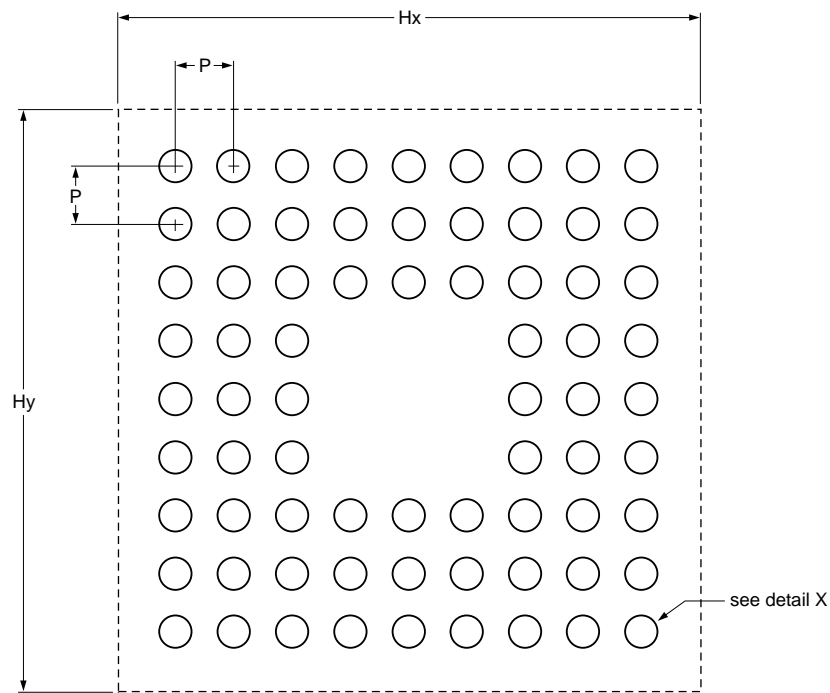
Generic footprint pattern

Refer to the package outline drawing for actual layout

◫ solder land

◩ solder paste deposit

▨ solder land plus solder paste

- - - - - occupied area

— · — solder resist

detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.40	0.250	0.275	0.350	9.400	9.400